



**SLOVENSKI STANDARD**  
**SIST EN 62047-10:2011**  
**01-december-2011**

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**Polprevodniški elementi - Mikroelektromehanski elementi - 10. del: Preskusi z mikrostebričnim pritiskom materialov za mikroelektromehanske sisteme (MEMS)**

Semiconductor devices - Microelectromechanical devices - Part 10: Micro-pillar compression test for MEMS materials

Halbleiterbauelemente - Bauelemente der Mikrosystemtechnik - Teil 10: Druckprüfverfahren an zylinderförmigen Mikroproben für Werkstoffe der Mikrosystemtechnik

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Dispositifs à semiconducteur - Dispositifs microélectromécaniques - Partie 10: Essai de compression utilisant la technique des micro-piliers pour les matériaux des MEMS

**Ta slovenski standard je istoveten z: EN 62047-10:2011**

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**ICS:**

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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**SIST EN 62047-10:2011**

**en**

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EUROPEAN STANDARD  
NORME EUROPÉENNE  
EUROPÄISCHE NORM

**EN 62047-10**

September 2011

ICS 31.080.99

English version

**Semiconductor devices -  
Micro-electromechanical devices -  
Part 10: Micro-pillar compression test for MEMS materials  
(IEC 62047-10:2011)**

Dispositifs à semiconducteur -  
Dispositifs microélectromécaniques -  
Partie 10: Essai de compression utilisant  
la technique des micro-piliers pour les  
matériaux des MEMS  
(CEI 62047-10:2011)

Halbleiterbauelemente -  
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zylinderförmigen Mikroproben für  
Werkstoffe der Mikrosystemtechnik  
(IEC 62047-10:2011)

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Management Centre: Avenue Marnix 17, B - 1000 Brussels**

## Foreword

The text of document 47F/85/FDIS, future edition 1 of IEC 62047-10, prepared by SC 47F, Micro-electromechanical systems, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62047-10:2011.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2012-05-30
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2014-08-30

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62047-8	-	Semiconductor devices - Micro-electromechanical devices - Part 8: Strip bending test method for tensile property measurement of thin films	EN 62047-8	-

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Edition 1.0 2011-07

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Semiconductor devices – Micro-electromechanical devices –  
Part 10: Micro-pillar compression test for MEMS materials**

**Dispositifs à semiconducteur – Dispositifs microélectromécaniques –  
Partie 10: Essai de compression utilisant la technique des micro-piliers pour  
les matériaux des MEMS**

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## CONTENTS

FOREWORD.....	3
1 Scope.....	5
2 Normative references .....	5
3 Symbols and designations .....	5
4 Test piece .....	6
4.1 General .....	6
4.2 Shape of test piece .....	6
4.3 Measurement of dimensions .....	6
5 Testing method and test apparatus.....	7
5.1 Test principle .....	7
5.2 Test machine.....	7
5.3 Test procedure .....	8
5.4 Test environment.....	8
6 Test report.....	8
Annex A (informative) Error estimation using finite element method .....	10
Bibliography.....	11
Figure 1 – Shape of cylindrical pillar (See Table 1 for symbols) .....	5
Figure 2 – Schematic of Micro-pillar compression test.....	7
Figure A.1 – Error estimation with the aspect ratio and friction coefficient in the elastic modulus measurement.....	10
SIST.EN.62047-10:2011	
<a href="https://standards.iteh.ai/catalog/standards/sist/83e05492-b877-4456-8ddc-6bd83099757c/sist-en-62047-10-2011">https://standards.iteh.ai/catalog/standards/sist/83e05492-b877-4456-8ddc-6bd83099757c/sist-en-62047-10-2011</a>	
Table 1 – Symbols and designations of test piece.....	6



## INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –  
MICRO-ELECTROMECHANICAL DEVICES –

**Part 10: Micro-pillar compression test for MEMS materials**

FOREWORD

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International Standard IEC 62047-10 has been prepared by subcommittee 47F: Micro-electromechanical systems, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47F/85/FDIS	47F/94/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 62047, under the general title *Semiconductor devices – Micro-electromechanical devices*, can be found on the IEC website.